

$1200V / 9m\Omega$ SiC MOSFET Power Module

Features

- High-speed switching possible
- Very low switching losses
- High blocking voltage with low on-resistance
- Temperature independent turn-off switching losses
- Ultra-low thermal resistance
- Common source topology
- Isolated back-side



Applications

- Solar power optimizer
- UPS system
- Solid state circuit breaker
- High power converters
- Photovoltaics, wind power generation
- Induction heating equipment
- Smart grid transmission and distribution

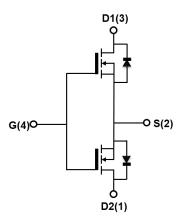


Table 1 Key performance and package parameters

Туре	$ m V_{DS}$	I_{DS} $(T_C = 25^{\circ}C, R_{th (j-c,max)})$	$\begin{aligned} \textbf{RDS(ON), typ} \\ (V_{GS} = 18\text{V}, I_D = 100\text{A}, \\ & T_J = 25^{\circ}\text{C}) \end{aligned}$	$T_{ m j,max}$	Package
S1P09R120CSE-A	1200V	240A	9mΩ	175°C	SOT227



1200V SiC Power MOSFET Module

Table of contents

Table of contents

Features	1
Applications	1
Table of contents	2
1. Maximum ratings	3
2. Thermal / Packaging Characteristics	4
3. Electrical characteristics	5
4. Package drawing	7
5、Test conditions	8
Revision history	9
Attention	Q



1200V SiC Power MOSFET Module

1. Maximum ratings

Table 2 Maximum rating ($Tc = 25^{\circ}C$ unless otherwise specified)

Symbol	Parameter	Value	Unit	Test Conditions	Note
V _{DS,max}	Drain source voltage	1200	V	$V_{GS} = 0V, I_D = 100 \mu A$	
$V_{GS,max}$	Gate source voltage	-8 /+22	V	Absolute maximum values	
V_{GSop}	Gate source voltage	-4 /+18	V	Recommended operational values	
т	Continuous dusin summent	240	A	$V_{GS} = 18V, T_C = 25^{\circ}C$	
I_D	Continuous drain current	160	A	$V_{GS} = 18V, T_C = 100^{\circ}C$	
I _{D(pulse)}	Pulsed drain current	480	A	Pulse width tp limited by T _j ,max	
P_{D}	Power dissipation	375	W	$T_C = 25^{\circ}C, T_J = 175^{\circ}C$	
T_{J} , T_{stg}	Operating Junction and storage temperature	-55 to +175	°C		



1200V SiC Power MOSFET Module

2. Thermal / Packaging Characteristics

Table 3 Package Characteristics

Symbol	Description		Тур.	Max.	Unit	Note
R _{th-JC}	Thermal Resistance, Junction to Case	-	0.4	ı	°C/W	
V _{ISO}	Isolation Test Voltage RMS, f=50Hz, t=1min	2.5	-	-	kV	
Croomaga	Terminal to Heatsink Creepage Distance	-	8.5	-	mm	
Creepage	Terminal to Terminal Creepage Distance	-	10.5	-	mm	
Classia	Terminal to Heatsink Clearance	-	6.8	-	mm	
Clearance	Terminal to Terminal Clearance	-	4.4	-	mm	
$T_{ m jmax}$	Maximum Junction Temperature		175	-	°C	
T_{jop}	Operation Junction Temperature		-55 to +175	-	°C	
T_{STG}	Storage Temperature Range		-55 to +175	-	°C	
W	Weight		28.5	-	g	
T_{M}	Screws to Heatsink Mounting Torque	-	-	1.5	N∙m	
T_{C}	Terminal Connection Torque (M4 *8mm)	-	-	1.3	N⋅m	

 $^{^{\}rm 1}$ Not subject to production test. Parameter verified by design/characterization.



1200V SiC Power MOSFET Module

3, Electrical characteristics

Table 4 SiC MOSFET characteristics ($Tc = 25^{\circ}C$ unless otherwise specified)

Symbol	Parameter	Min.	Тур.	Max.	Unit	Test Conditions N	Note
V _{(BR)DSS}	Drain-source breakdown voltage	1200	-	-	V	$V_{GS} = 0V, I_D = 100 \mu A$	
		2.3	2.8	4.0	V	$V_{DS} = V_{GS}, I_D = 40 mA$	
V _{GS(th)}	Gate threshold voltage	-	2.0	-	V	$V_{DS} = V_{GS}$, $I_D = 40$ mA, $T_J = 175$ °C	
I_{DSS}	Zero gate voltage drain current	-	1	10	μΑ	$V_{DS} = 1200V, V_{GS} = 0V$	
I_{GSS}	Gate source leakage current	-	-	100	nA	$V_{GS} = 18V, V_{DS} = 0V$	
	Current drain-source	-	8.5	11		$V_{GS} = 18V, I_D = 140A$	
R _{DS(on)}	on-state resistance	-	13.5	-		$V_{GS} = 18V, I_D = 140A,$ $T_J = 175^{\circ}C$	
		-	118	-		$V_{DS} = 20V, I_D = 140A$	
gfs	Transconductance	-	98	-	S	$V_{DS} = 20V, I_D = 140A,$ $T_J = 175^{\circ}C$	
$R_{g,int}$	Internal gate resistance	-	1.0	-	Ω	$V_{AC} = 25 \text{mV}, f = 1 \text{MHz},$ open drain	
C _{iss}	Input capacitance	-	8521	-		$V_{DS} = 1000V, V_{GS} = 0V$	
C_{oss}	Output capacitance	-	347	-	pF	$T_J = 25^{\circ}C, V_{AC} = 25mV$	
C _{rss}	Reverse capacitance	-	15	-		f = 100KHz	
Q_{gs}	Gate source charge	-	54	-		$V_{DS} = 800V,$	
Qgd	Gate drain charge	-	45	-	пC	$V_{GS} = -4/+18V$	
Qg	Gate charge	-	230	-		$I_D = 100A$	

^{*} By estimated



1200V SiC Power MOSFET Module

Eon	Turn on switching energy	-	812	-		
E _{off}	Turn off switching energy	-	383	-	μJ	
t_{d} (on)	Turn on delay time	-	19	-		$V_{DS} = 800V, V_{GS} = -4/+18V$
t _r	Rise time	-	29	-		$I_D = 100A, Rg = 2.5\Omega,$ $L = 16.7\mu H$
t _d (off)	Turn off delay time	-	42	-	ns	
t_{f}	Fall time	-	9.3	-		

Table 5 Body diode characteristics

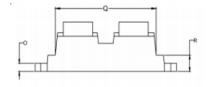
Symbol	Parameter	Min.	Тур.	Max.	Unit	Test Conditions	Note
		-	3.8	-	V	$V_{GS} = -4V, I_{SD} = 70A$	Fig.8,9,
V_{SD}	Diode forward voltage	-	3.6	-	V	$V_{GS} = -4V$, $I_{SD} = 70A$ $T_J = 175$ °C	10
I_S	Continuous diode forward current	-	240	-	A	$V_{GS} = -4V$, $Tc = 25$ °C	
t _{rr}	Reverse recovery time	-	66	-	ns	$V_R = 800V, V_{GS} = -4V$	
Qrr	Reverse recovery charge	-	1830	-	nC	$I_D = 100A$	
I_{rrm}	Peak reverse recovery current	-	52	-	A	$T_J = 175^{\circ}C$	

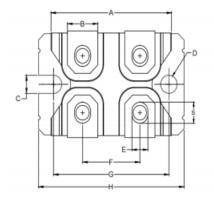
Note : When using SiC Body Diode the maximum recommended $V_{\text{GS}} = \text{-4 V}$

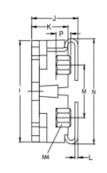


1200V SiC Power MOSFET Module

4. Package drawing





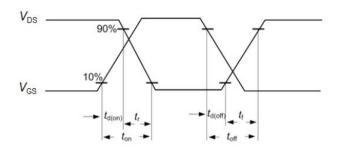


DiM	Millin	neter		
DIIVI	Min	Max		
Α	31.40	31.60		
В	7.70	8.10		
B C	4.20	4.40		
D	4.20	4.40		
D E F	4.10	4.30		
F	14.90	15.10		
G	30.10	30.20		
Н	38.00	38.40		
	23.80	24.20		
J	11.80	12.20		
K	9.40	9.60		
L	0.75	0.85		
M	12.40	12.80		
N	24.50	25.40		
0	1.90	2.10		
Р	3.10	3.95		
Q	26.60	27.00		
R	3.80	4.20		
S	5.10	5.40		

Datasheet



5. Test conditions



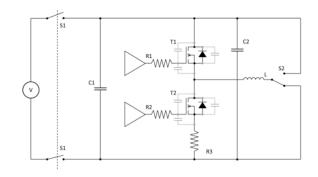


Figure A. Definition of switching times

Figure B. Dynamic test circuit

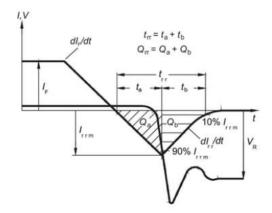


Figure C. Definition of diode switching characteristics

Figure C. Definition of body diode switching characteristics



Revision history

Document version	Date of release	Description of changes	
V01_00	2024-05-26		

Attention

1. Rohs compliance

The levels of RoHS restricted materials in this product are below the maximum concentration values (also referred to as the threshold limits) permitted for such substances, or are used in an exempted application, in accordance with EU Directive 2011/65/ EC (RoHS2), as implemented January 2, 2013.

2. REACH compliance

REACH substances of high concern (SVHCs) information is available for this product. Since the European Chemical Agency (ECHA) has published notice of their intent to frequently revise the SVHC listing for the foreseeable future, please contact a Sichain representative to insure you get the most up-to-date REACH SVHC Declaration. REACH banned substance information (REACH Article 67) is also available upon request.

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